



Material Content Data Sheet



Sales Product Name	ESD129-B1-CSP01005 E63				Issued		7. September 2015		
MA#	MA001346974								
Package	SG-WLL-2-2				Weight*		0.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.039	92.40	92.40	923936	923936	
pad	inorganic material	phosphorus	7723-14-0	0.000	0.13		1339		
	noble metal	gold	7440-57-5	0.000	0.14		1410		
	noble metal	palladium	7440-05-3	0.000	0.88		8788		
	non noble metal	nickel	7440-02-0	0.003	6.45	7.60	64527	76064	
*deviation	< 10%	Sum in total:				100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com